

VIII. We Claim:

1. An electrical device including:
a base;
a conductive layer adjacent to the base;
a dielectric material adjacent to conductive layer;
a tooth structure including a metal layer set in the dielectric
material, but not set in the conductive layer, to join the dielectric material to the metal layer; and
wherein the metal layer forms a portion of multiple layers of circuitry in an
electrical device.

2. A method of making the electrical device of claim 1, the method
comprising the following steps:

providing a base;
adding a conductive layer to the base;
applying a dielectric material to the conductive layer;
forming cavities in the applied dielectrical material;
applying a conductive coating to the cavities in the dielectrical material;
forming a metal layer on the conductive coating to produce a tooth structure set
in the dielectric coating but not set in the conductive layer;
forming openings in the dielectric coating; and
forming circuitry through a multilayer electrical device.

3. The method of claim 2, wherein the step of applying a dielectrical material
and the step of forming a metal layer are carried out to produce a peel strength greater than the
peel strength than that of a single desmear process.

4. The method of claim 2, wherein the step of adding a conductive layer to the base is carried out by an oxide process.

5. The method of claim 2, wherein the step of adding a conductive layer to the base is carried out by an oxide replacement process.

6. The method of claim 2, wherein:
the step of applying a conductive coating is carried out by direct plating on the dielectrical material.

7. The method of claim 2, wherein the step of forming is carried out by a double desmear process.

8. An electrical device made by the process of claim 2.